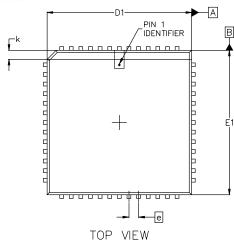
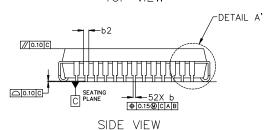


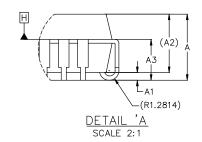


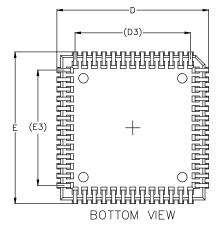
## PLCC52 19.13x19.13x3.80, 1.27P CASE 776AF ISSUE B

**DATE 15 AUG 2025** 









DIM	MILLIMETERS		
	MIN.	NOM.	MAX.
А	4.19	4.38	4.57
A1	0.12		
A2	3.80 REF.		
А3	2.54	2.67	2.79
b	0.33	0.43	0.53
b2	0.66	0.74	0.81
D	19.94	20.07	20.19
D1	19.05	19.13	19.20
D2	17.53	18.04	18.54
D3	15.24 REF.		
Е	19.94	20.07	20.19
E1	19.05	19.13	19.20
E2	17.53	18.04	18.54
E3	15.24 REF.		
е	1.27 BSC		
k	1.07	1.15	1.22

- 1. DIMENSIONING AND TOLERANCING CONFORM TO ASME Y14.5M-2018.
- 2. ALL DIMENSION ARE IN MILLIMETERS (mm).
- 3. DATUM PLANE H LOCATED AT TOP OF MOLD PARTING LINE AND COINCIDENT WITH TOP OF LEAD. WHERE THE LEAD EXIST PLASTIC BODY.
- 4. DIMENSION D1 AND E1 DO NOT INCLUDE MOLD PROTRUSION. ALLOWABLE MOLD PROTRUSION IS 0.25MM.
- 5. PIN 1 IDENTIFIER MUST BE LOCATED WITHIN THE ZONE AREA.

**GENERIC** 

**MARKING DIAGRAM\*** 

XXXX = Specific Device Code Y = Year

Y = Year ZZZ = Assembly Lot Code \*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "•", may or may not be present. Some products may not follow the Generic Marking.

## DOCUMENT NUMBER:

98AON31341E

Electronic versions are uncontrolled except when accessed directly from the Document Repository. Printed versions are uncontrolled except when stamped "CONTROLLED COPY" in red.

DESCRIPTION:

PLCC52 19.13x19.13x3.80, 1.27P

PAGE 1 OF 1

onsemi and ONSEMI are trademarks of Semiconductor Components Industries, LLC dba onsemi or its subsidiaries in the United States and/or other countries. onsemi reserves the right to make changes without further notice to any products herein. onsemi makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does onsemi assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. onsemi does not convey any license under its patent rights nor the rights of others.